

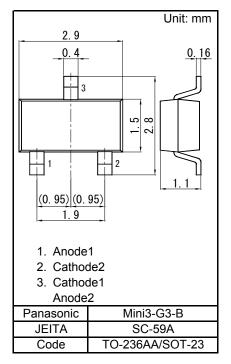
DA3X101F0L Silicon epitaxial planar type

For high speed switching circuits DA3J101F in Mini3 type package

#### Features

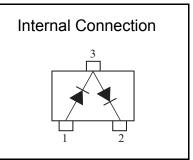
- Small reverse current IR
- Short reverse recovery time trr
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 22
- Basic Part Number : Dual DA2J101 (Series)
- Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



#### Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit	
Reverse voltage		VR	80	V	
Maximum peak reverse voltage		VRM	80	V	
Forward current	Single	IF	100	mA	
	Series		65	mA	
Peak forward current	Single	IFM	225	mA	
	Series		145	mA	
Non-repetitive peak	Single	IFSM	500	mA	
forward surge current *1	Series		325	mA	
Junction temperature		Tj	150	°C	
Operating ambient temperature		Topr	-40 to +85	С°	
Storage temperature		Tstg	-55 to +150	°C	



Note) \*1: t = 1 s

Switching Diode DA3X101F0L

## **Panasonic**

# Switching Diode DA3X101F0L

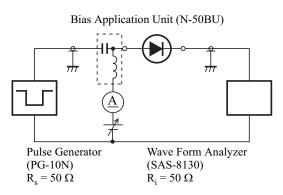
### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

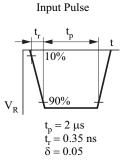
Parameter	Symbol	Conditions	Min	Тур	Max	Unit			
Forward voltage	VF	IF = 100 mA			1.2	V			
Reverse voltage	VR	IR = 100 μA	80			V			
Reverse current	IR	VR = 80 V			100	nA			
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz			1.2	pF			
Reverse recovery time <sup>*1</sup>	trr	IF = 10 mA, VR = 6 V		3	3	ns			
	ui	Irr = 0.25 × IR			5				

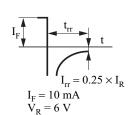
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 100 MHz.

3. \*1: trr test circuit





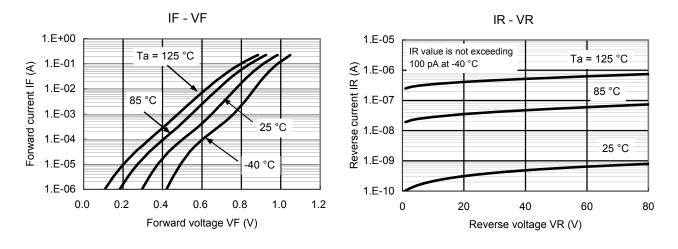


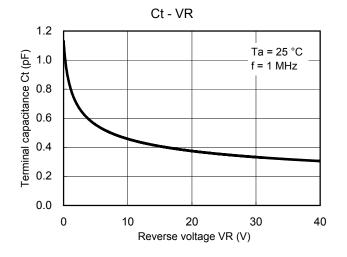
Output Pulse



Switching Diode DA3X101F0L

## Technical Data (reference)



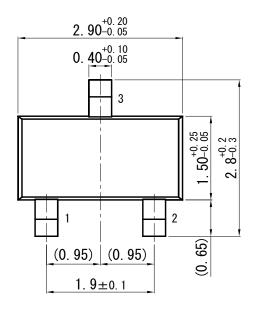


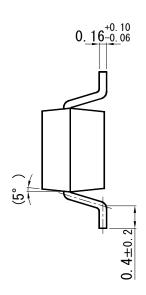


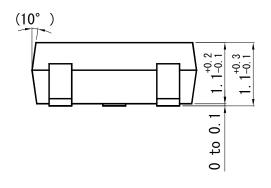
Mini3-G3-B

Switching Diode DA3X101F0L

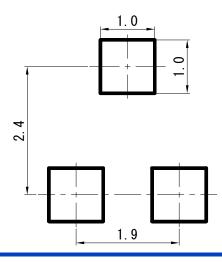
Unit: mm







Land Pattern (Reference) (Unit: mm)



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